Features• RDS(ON), VGS@10V, ID@500mA<1.45Ω• RDS(ON), VGS@4.5V, ID@200mA<1.95Ω• RDS(ON), VGS@2.5V, ID@100mA<4.0Ω• RDS(ON), VGS@1.8V, ID@10mA<6.0Ω• Advanced Trench Process Technology• ESD Protected 2KV HBM• Specially Designed for Relay driver, Speed line drive, etc.• Lead free in compliance with EU RoHS 2.0• Green molding compound as per IEC 61249 standardMechanical Data• Case : SOT-563 Package• Terminals : Solderable per MIL-STD-750, Method 2026	Voltage 50 V Current 360 mA	SOT-563	Unit : inch(mm
RDS(ON), VGS@4.5V, ID@200mA<1.95ΩRDS(ON), VGS@2.5V, ID@100mA<4.0ΩRDS(ON), VGS@1.8V, ID@10mA<6.0ΩAdvanced Trench Process TechnologyESD Protected 2KV HBMSpecially Designed for Relay driver, Speed line drive, etc.Lead free in compliance with EU RoHS 2.0Green molding compound as per IEC 61249 standardMechanical DataCase : SOT-563 PackageTerminals : Solderable per MIL-STD-750, Method 2026			30) 10) 10) 10) 10) 10) 10) 10) 1
RDS(ON), VGS@4.5V, ID@200mA<1.95 Ω RDS(ON), VGS@2.5V, ID@100mA<4.0 Ω RDS(ON), VGS@1.8V, ID@10mA<6.0 Ω Advanced Trench Process Technology ESD Protected 2KV HBM Specially Designed for Relay driver, Speed line drive, etc. Lead free in compliance with EU RoHS 2.0 Green molding compound as per IEC 61249 standard Mechanical Data Case : SOT-563 Package Terminals : Solderable per MIL-STD-750, Method 2026	RDS(ON) , VGS@10V, ID@500mA<1.45Ω	067(1.70) 056(1.50) 044(1.10) 035(0.90)	
RDS(ON), VGS@1.8V, ID@10mA<6.0Ω	RDS(ON) , VGS@4.5V, ID@200mA<1.95Ω		
RDS(ON) , VGS@1.8V, ID@10mA<6.0Ω Advanced Trench Process Technology ESD Protected 2KV HBM Specially Designed for Relay driver, Speed line drive, etc. Lead free in compliance with EU RoHS 2.0 Green molding compound as per IEC 61249 standard Mechanical Data Case : SOT-563 Package Terminals : Solderable per MIL-STD-750, Method 2026	RDS(ON) , VGS@2.5V, ID@100mA<4.0Ω	_	007(0.17) 002(0.07)
Advanced Trench Process Technology ESD Protected 2KV HBM Specially Designed for Relay driver, Speed line drive, etc. Lead free in compliance with EU RoHS 2.0 Green molding compound as per IEC 61249 standard Mechanical Data Case : SOT-563 Package Terminals : Solderable per MIL-STD-750, Method 2026	RDS(ON) , VGS@1.8V, ID@10mA<6.0Ω		
 Specially Designed for Relay driver, Speed line drive, etc. Lead free in compliance with EU RoHS 2.0 Green molding compound as per IEC 61249 standard Mechanical Data Case : SOT-563 Package Terminals : Solderable per MIL-STD-750, Method 2026 	Advanced Trench Process Technology	-	
Lead free in compliance with EU RoHS 2.0 Green molding compound as per IEC 61249 standard Mechanical Data Case : SOT-563 Package Terminals : Solderable per MIL-STD-750, Method 2026	ESD Protected 2KV HBM		
 Green molding compound as per IEC 61249 standard Mechanical Data Case : SOT-563 Package Terminals : Solderable per MIL-STD-750, Method 2026 	Specially Designed for Relay driver, Speed line drive, etc.		K
Green molding compound as per IEC 61249 standard Mechanical Data • Case : SOT-563 Package • Terminals : Solderable per MIL-STD-750, Method 2026	Lead free in compliance with EU RoHS 2.0		
Mechanical Data 6 5 4 • Case : SOT-563 Package • <td>Green molding compound as per IEC 61249 standard</td> <td></td> <td></td>	Green molding compound as per IEC 61249 standard		
Terminals : Solderable per MIL-STD-750, Method 2026	Mechanical Data		
	Case : SOT-563 Package		
	Terminals : Solderable per MIL-STD-750, Method 2026		└┿┤╠╬╏╋║ ─╇┐╶┡┙║
Approx. Weight : 0.0026 grams	Approx. Weight : 0.0026 grams		

Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS
Drain-Source Voltage		V _{DS}	50	V
Gate-Source Voltage		V _{GS}	<u>+</u> 20	V
Continuous Drain Current		ID	360	mA
Pulsed Drain Current		Ідм	1200	mA
Power Dissipation	T _A =25°C		300	mW
	Derate above 25°C	PD	2.4	mW/°C
Operating Junction and Storage Temperature Range		TJ,TSTG	-55~150	٥C
 Typical Thermal Resistance Junction to Ambient^(Note 3) 		R _{θJA}	417	°C/W

PAN<mark>JİT</mark>



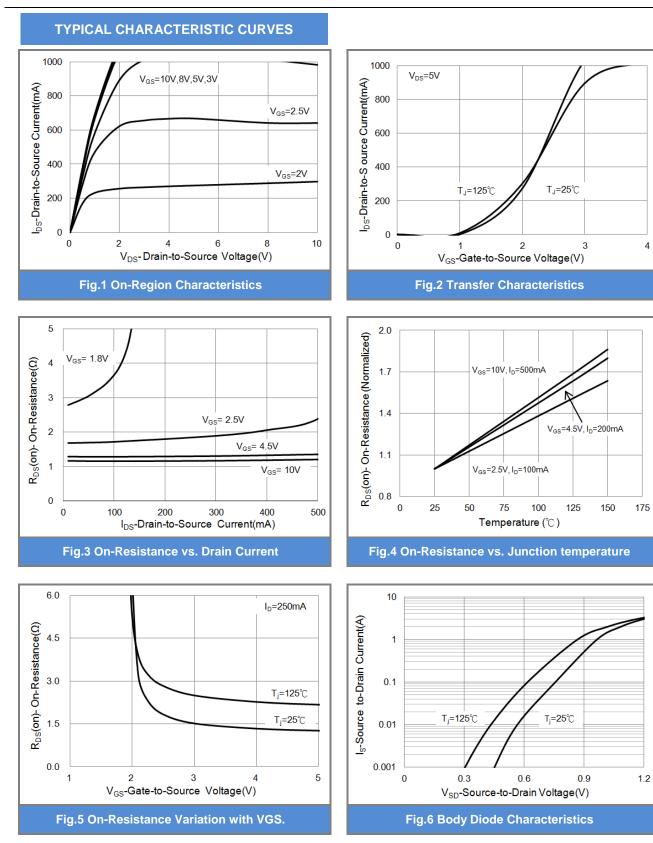
Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _D =250uA	50	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	0.5	0.86	1.0	V
Drain-Source On-State Resistance		V _{GS} =10V,I _D =500mA	-	1.2	1.45	- Ω
	Deserve	V _{GS} =4.5V,I _D =200mA	-	1.3	1.95	
	R _{DS(on)}	V _{GS} =2.5V,I _D =100mA	-	1.7	4.0	
		V _{GS} =1.8V,I _D =10mA	-	4.0	6.0	
Zero Gate Voltage Drain Current	IDSS	V _{DS} =50V,V _{GS} =0V	-	-	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} = <u>+</u> 20V,V _{DS} =0V	-	-	<u>+</u> 10	uA
Dynamic ^(Note 4)						
Total Gate Charge	Qg	V _{DS} =25V, I _D =500mA, V _{GS} =4.5V	-	0.95	-	nC
Gate-Source Charge	Qgs		-	0.34	-	
Gate-Drain Charge	Q _{gd}	VGS=4.5V	-	0.32	-	
Input Capacitance	Ciss		-	36	-	pF
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V, f=1.0MHZ	-	11	-	
Reverse Transfer Capacitance	Crss		-	6.6	-	
Turn-On Delay Time	td _(on)		-	2.3	-	
Turn-On Rise Time	tr	V _{DD} =25V, I _D =500mA, V _{GS} =10V,	-	20	-	ns
Turn-Off Delay Time	td _(off)	$V_{GS} = 10V$, R _G =6 $\Omega^{(Note 1,2)}$	-	7	-	
Turn-Off Fall Time	tf		-	20	-	
Drain-Source Diode			_	_	_	_
Maximum Continuous Drain-Source Diode Forward Current	ls		-	-	500	mA
Diode Forward Voltage	V _{SD}	Is=500mA, V _{GS} =0V	-	0.9	1.5	V

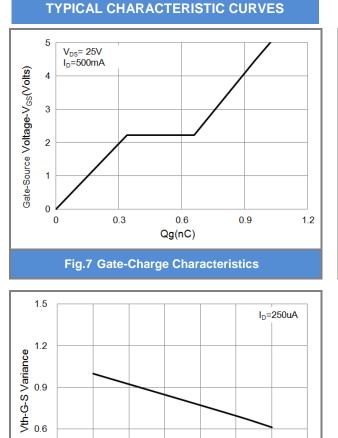
NOTES :

- 1. Pulse width</br>
- 2. Essentially independent of operating temperature typical characteristics.
- 3. R_{®JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. mounted on a 1 inch square pad of copper
- 4. Guaranteed by design, not subject to production testing.











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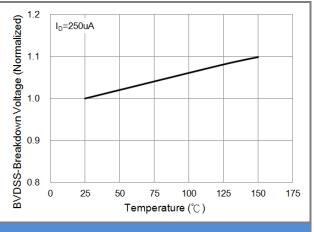
Temperature (℃)

100

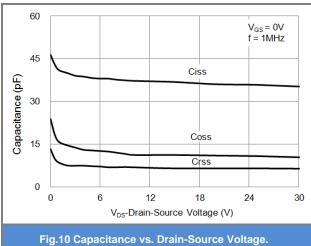
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150

175







0.3

0

25

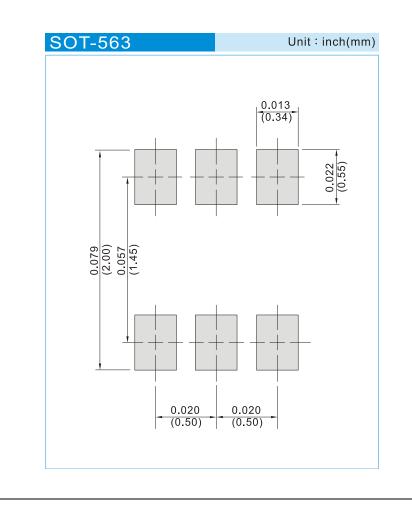
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PART NO. PACKING CODE VERSION

Part No. Packing Code	Package Type	Packing Type	Marking	Version
PJX8838_R1_00001	SOT-563	4K pcs / 7" reel	X38	Halogen free RoHS compliant
PJX8838_R2_00001	SOT-563	10K pcs / 13" reel	X38	Halogen free RoHS compliant

MOUNTING PAD LAYOUT





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